

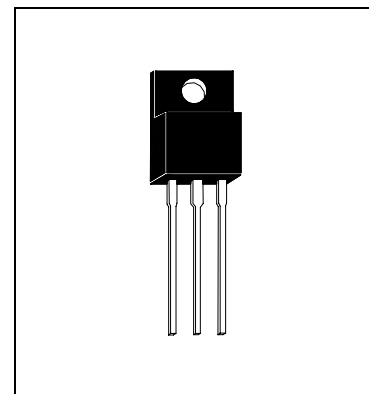


HSBF857

PNP EPITAXIAL PLANAR TRANSISTOR

Description

Low frequency power amplifier.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55~+150°C
Junction Temperature 150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 30 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 70 V
BVCEO Collector to Emitter Voltage 50 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 4 A
IC Collector Current (IC Peak) 8 A

Characteristics (Ta=25°C)

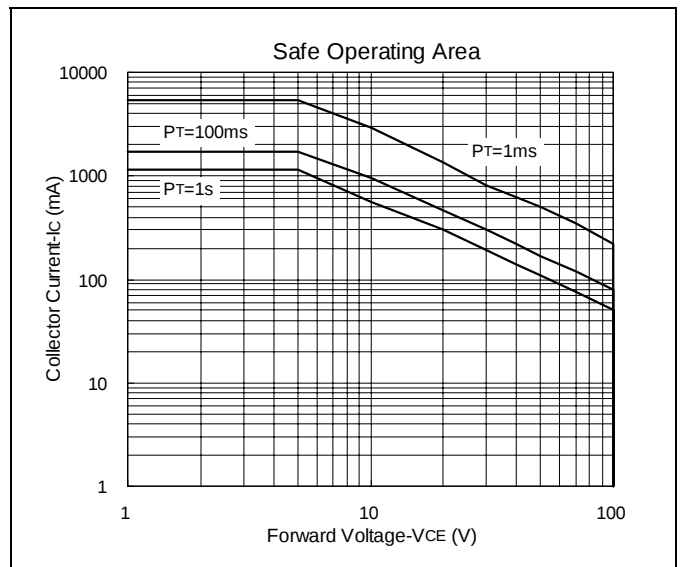
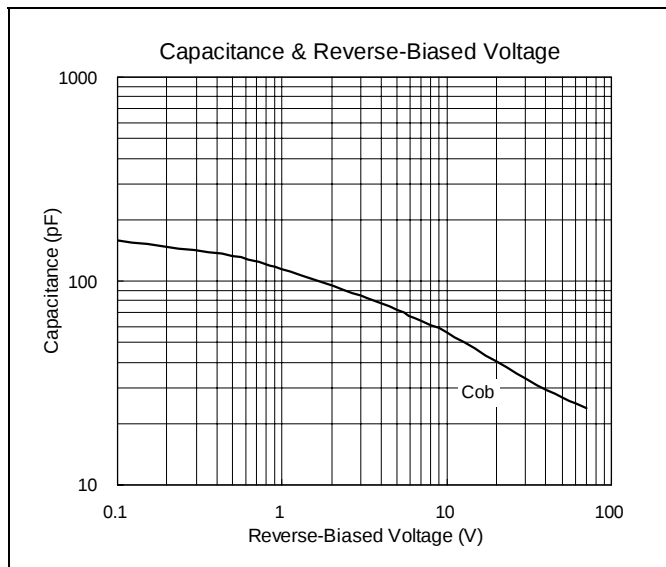
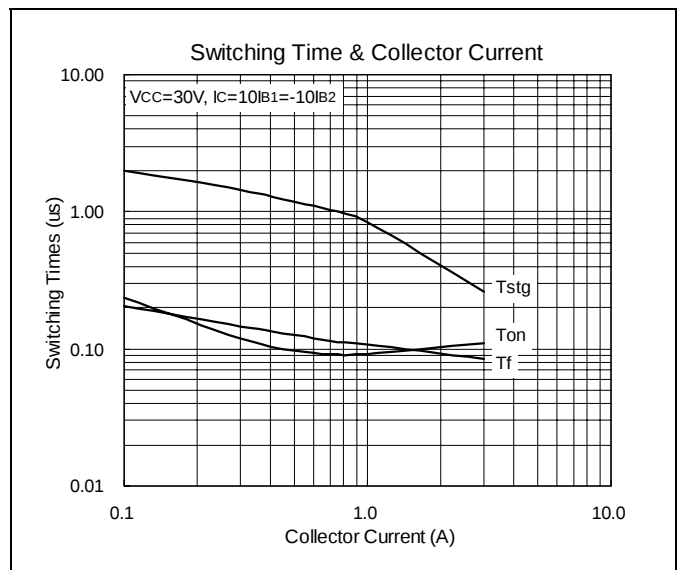
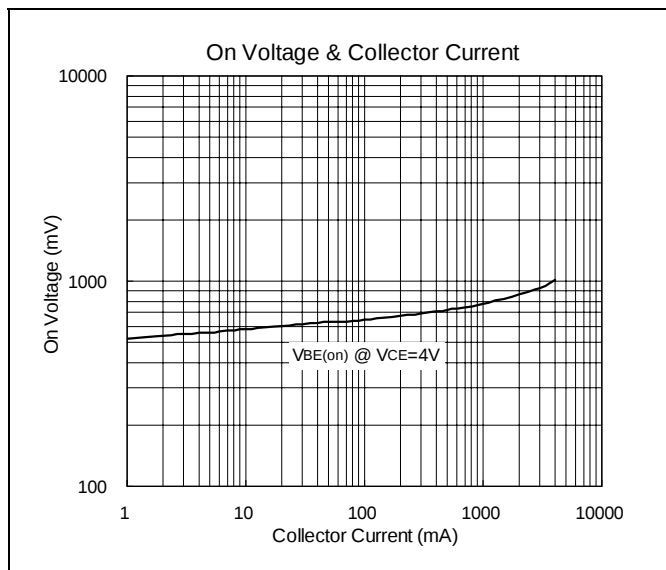
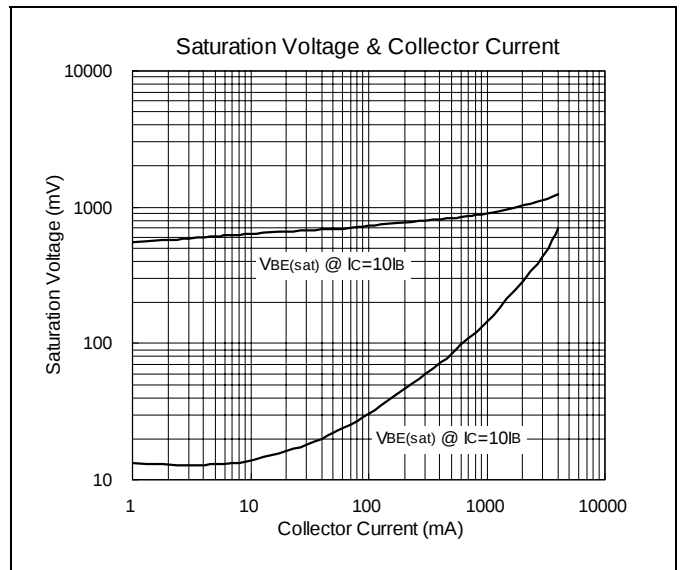
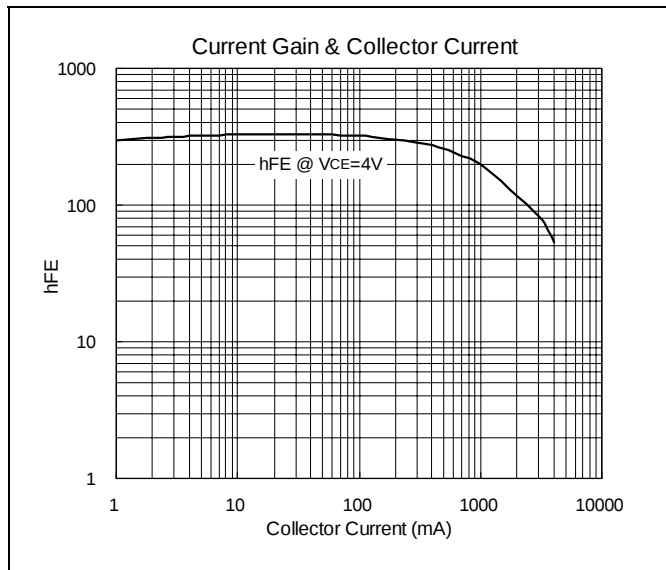
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	70	-	-	V	IC=10uA
BVCEO	50	-	-	V	IC=50mA
BVEBO	5	-	-	V	IC=10uA
ICBO	-	-	1	uA	VCB=50V
VCE(sat)	-	-	1	V	IC=2A, IB=0.2A
VBE(on)	-	-	1	V	IC=1A, VCE=4V
hFE1	35	-	-		IC=0.1A, VCE=4V
hFE2	60	-	320		IC=1A, VCE=4V
fT	-	15	-	MHz	VCE=4V, IC=500mA, f=100MHz

Classification Of hFE2

Rank	B	C	D
hFE	60-120	100-200	160-320

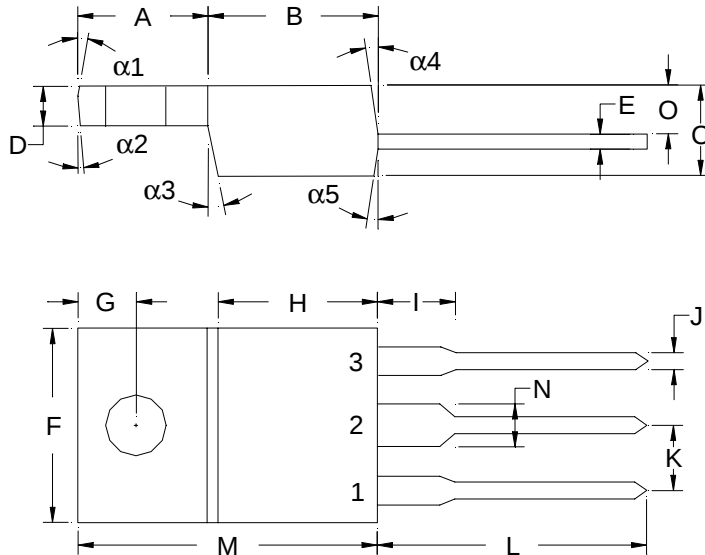


Characteristics Curve

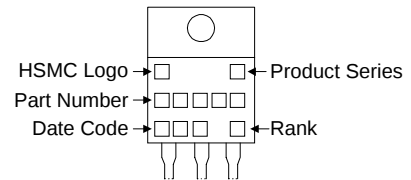




TO-220FP Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-220FP Plastic Package
HSMC Package Code : F

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5977061 Fax : 886-3-5979220